

SUPPORT FOR THE AMENDMENT

Claim 1 is currently amended.

Claims 13-18 are added.

Claim 1 has been amended for minor editorial purposes.

Support for the amendments to claims 13-18 can be found in the specification at page 8, lines 21-24, page 12, line 17 through page 13, line 8, page 17, lines 19-22, and page 18, lines 11-22, as originally filed.

No new matter has been added by the amendments. Accordingly, entry of the amendments is requested.

Upon entry of the amendments, claims 1-18 will be pending in the present application.

REQUEST FOR RECONSIDERATION

The present invention relates to an abrasive pad comprising:

“an abrasive substrate having a polishing surface and a light transmitting member which is fused to the abrasive substrate and comprises a water-insoluble matrix material and a water-soluble substance dispersed in the water-insoluble matrix material”. (Present claim 1). (Emphasis added). The above-underlined structural feature of the claimed invention is not described or suggested by the cited reference of record.

Accordingly, the rejection of claims 1-6 and 10-12 under 35 U.S.C. § 102(b) as anticipated by EP 1252973 (“EP ‘973”) is respectfully traversed. Reconsideration of the claimed invention is requested in light of the following.

EP ‘973 generally describes a polishing pad for a semiconductor wafer comprising a water-insoluble matrix material and water-soluble practices dispersed in the water-insoluble matrix material and having light transmitting properties. However, according to the reference, the polishing pad “is comprised of a substrate for a polishing pad provided with a through hole penetrating from surface to back, and a light transmitting part *fitted* in the . . . through hole.” (Paragraph [0050]). (Emphasis added). That is, the light transmitting part is not fused with the substrate, and neither is there any suggestion do so.

In particular, the reference recites that the polishing pad “can retain . . . slurry on the surface thereof and, further, make wastages reside transiently.” (Paragraph [0051]). “In order to retain the slurry and make wastages reside transiently during polishing, it is preferable that at least fine holes or grooves are formed on the surface of the . . . substrate for polishing.” (Paragraph [0052]). (Emphasis added).

By contrast, one of the features of the claimed abrasive pad is that the light transmitting member *and* the abrasive substrate are fused together as set forth in claim 1. The term “fused” is defined in the present specification at page 16, 2nd paragraph, as follows:

The term ‘fused’ refers to a state in which the light transmitting member and the abrasive substrate are bonded together by melting at least the bonding surface(s) of both or one of them without using an adhesive. For the production of the abrasive pad, not only the bonding surface but also the entire light transmitting member may be molten to be bonded, or the entire abrasive substrate may be molten to be bonded.

(Emphasis added). As a result, “there is no gap between the light transmitting member and the abrasive substrate, whereby slurry does not leak to the rear side of the abrasive pad.”

(Present specification at page16, lines 31-33).

EP ‘973, as discussed above, clearly does not relate to any fusion of the polishing pad and light transmitting part whatsoever. Moreover, in light of the advantage of the above-mentioned “fine holes or grooves” formed on the surface of the disclosed polishing pad, there is clearly no motivation for fusing these components.

Therefore, the claimed invention is novel and unobvious over EP ‘973.

Accordingly, withdrawal of the rejection is requested.

Applicants submit that claims 13-18 are novel and unobvious over the cited reference, since these claims depend from claim 1, and the reference does not describe or suggest the features of claim 1 as discussed above.

Applicants thank Examiner Rachuba for withdrawing the Restriction Requirement concerning claim 12, and examining claims 1-6 and 10-12. However, Applicants respectfully request rejoinder of claims 7-9, in accordance with the provisions of MPEP § 821.04, since these claims depend from and include all of the limitations of claim 1.

Applicants submit that the application is now in condition for allowance. Early notification of such allowance is earnestly solicited.

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Should the Examiner deem that any further action is necessary to place this application in even better form for allowance, the Examiner is encouraged to contact Applicants' undersigned representative at the below listed telephone number.

Respectfully submitted,

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